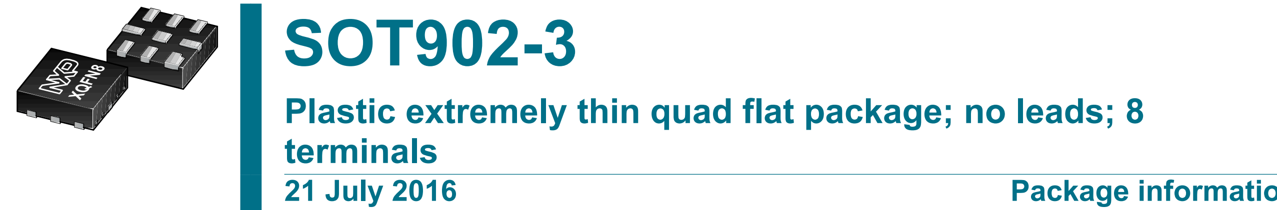

SOT902-3

Plastic extremely thin quad flat package; no leads; 8 terminals

21 July 2016 — Package information

1. Package summary

Dimensions (mm) 1.60 x 1.60 x 0.5

Terminal position code Q (quad)

Package type descriptive code XQFN8

Package outline version code SOT902-3

Manufacturer package code SOT902

Package type industry code XQFN8

Package outline version description Plastic extremely thin quad flat package; no leads; 8 terminals

Package style descriptive code XQFN (extremely thin quad flatpack; no leads)

Package body material type P

IEC package outline code ---

JEDEC package outline code MO-255

JEITA package outline code ---

Handling precautions IC26_CHAPTER_3_2000

Thermal design considerations IC26_CHAPTER_6_2000

Mounting method type S (surface mount)

Generic mounting and soldering information AN10365_3

Reflow soldering footprint SOT902-3_fr

Package life cycle status REL

Major version date 18-8-2011

Minor version date 14-5-2012

Security status COMPANY PUBLIC

Modified date 26-6-2012

Issue date 18-8-2011

Web publication date 28-11-2012

Initial web publication date 25-8-2011

Customer specific indicator N

Maturity Product

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
A_2	package height		-	-	-	-	
A	seated height		-	-	-	0.5	mm
D	package length		1.55	-	1.6	1.65	mm

Symbol	Parameter		Min	Typ	Nom	Max	Unit
E	package width		1.55	-	1.6	1.65	mm
e	nominal pitch		-	-	0.6	-	mm
n_2	actual quantity of termination		-	-	8	-	

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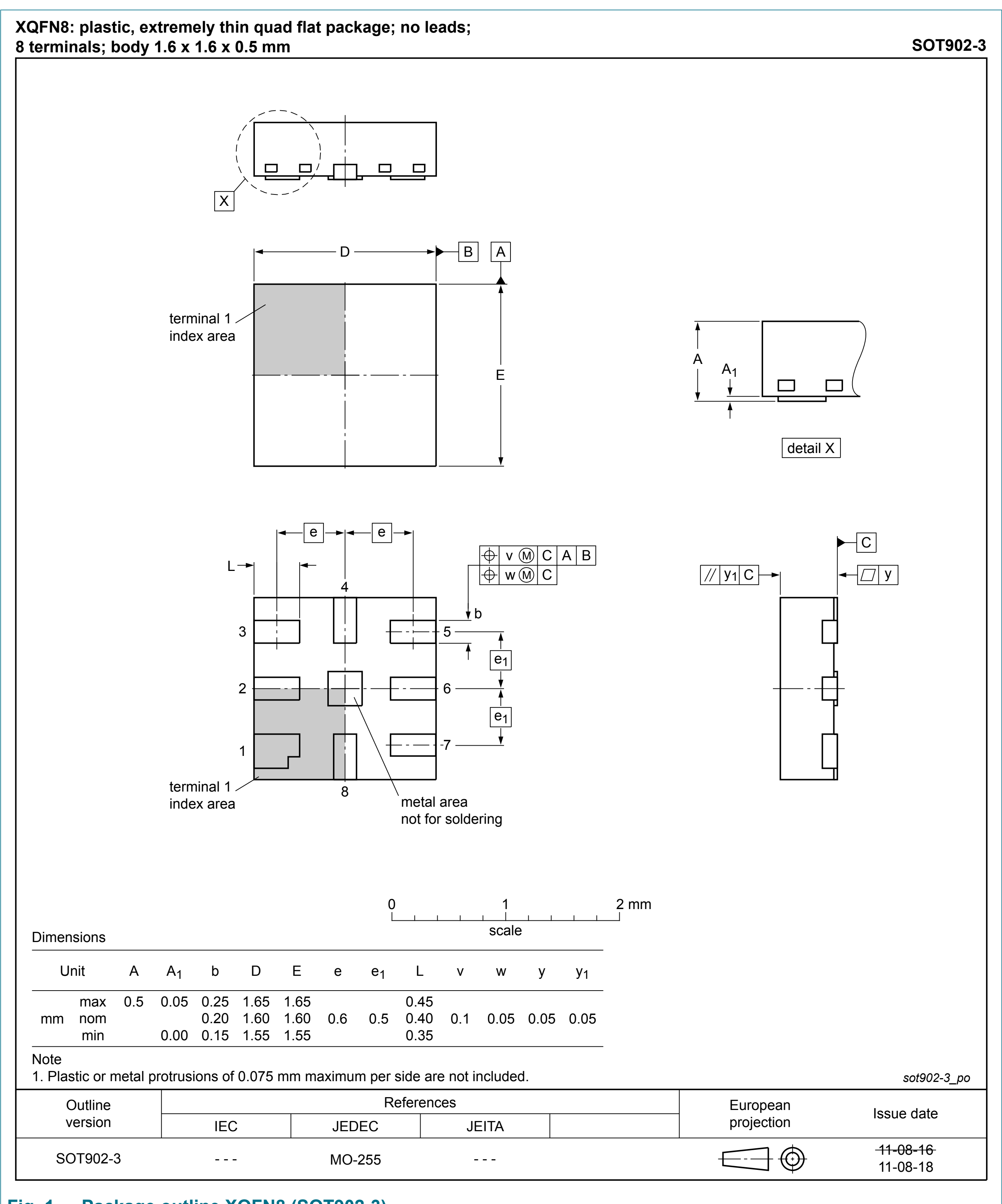
2. Package outline



Dimensions

Unit		A	A_1	b	D	E	e	e_1	L	v	w	y	y_1
	max	0.5	0.05	0.25	1.65	1.65			0.45				
mm	nom			0.20	1.60	1.60	0.6	0.5	0.40	0.1	0.05	0.05	0.05
	min		0.00	0.15	1.55	1.55			0.35				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT902-3	- - -	MO-255	- - -			~~11-08-16~~ 11-08-18

Fig. 1. Package outline XQFN8 (SOT902-3)

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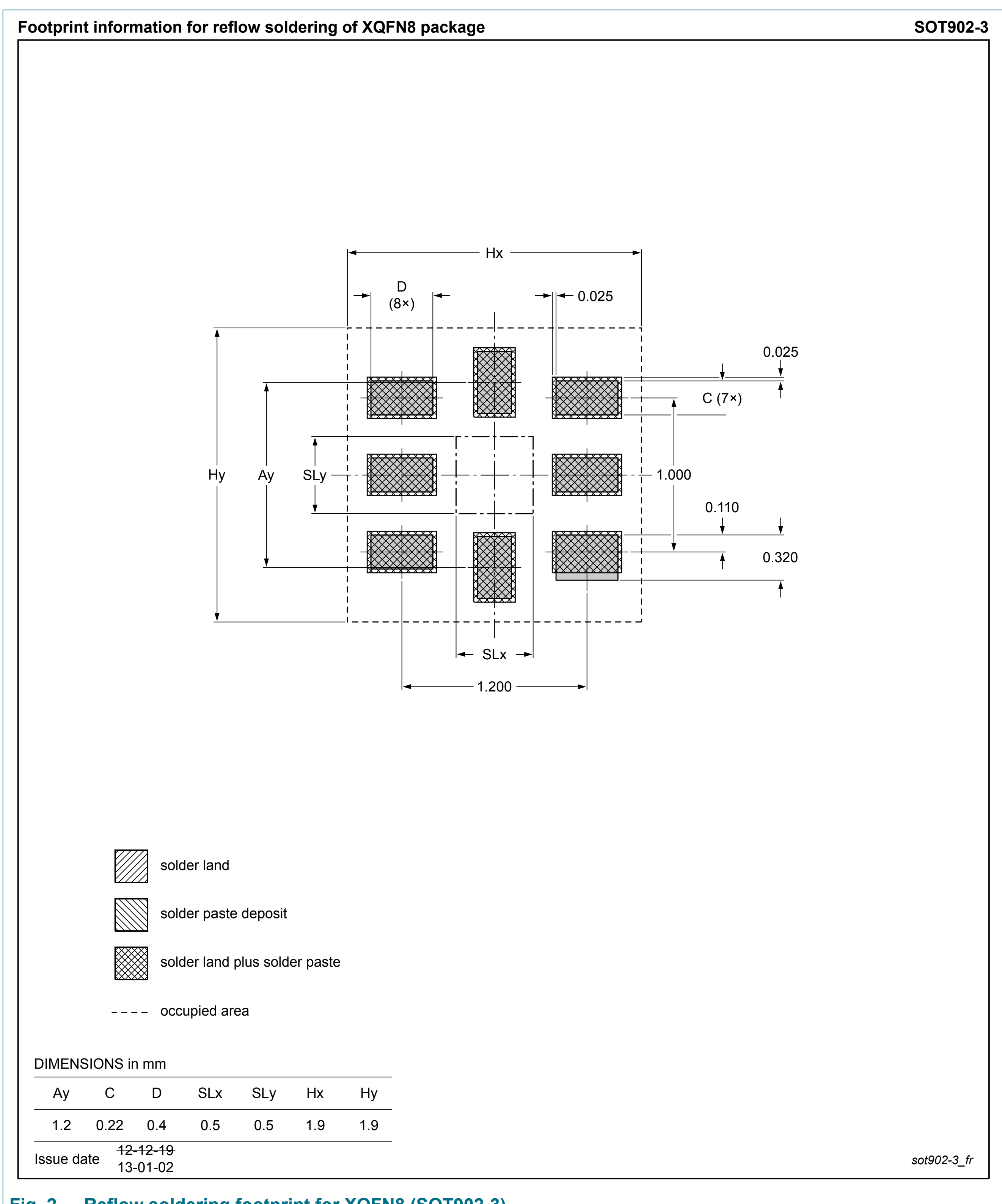
3. Soldering



DIMENSIONS in mm

Ay	C	D	SLx	SLy	Hx	Hy
1.2	0.22	0.4	0.5	0.5	1.9	1.9

Issue date ~~12-12-19~~ 13-01-02

Fig. 2. Reflow soldering footprint for XQFN8 (SOT902-3)

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5. Contents

1. Package summary... 1
2. Package outline.. 3
3. Soldering... 4
4. Legal information.. 5

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